

## Standard SCRs, 16A

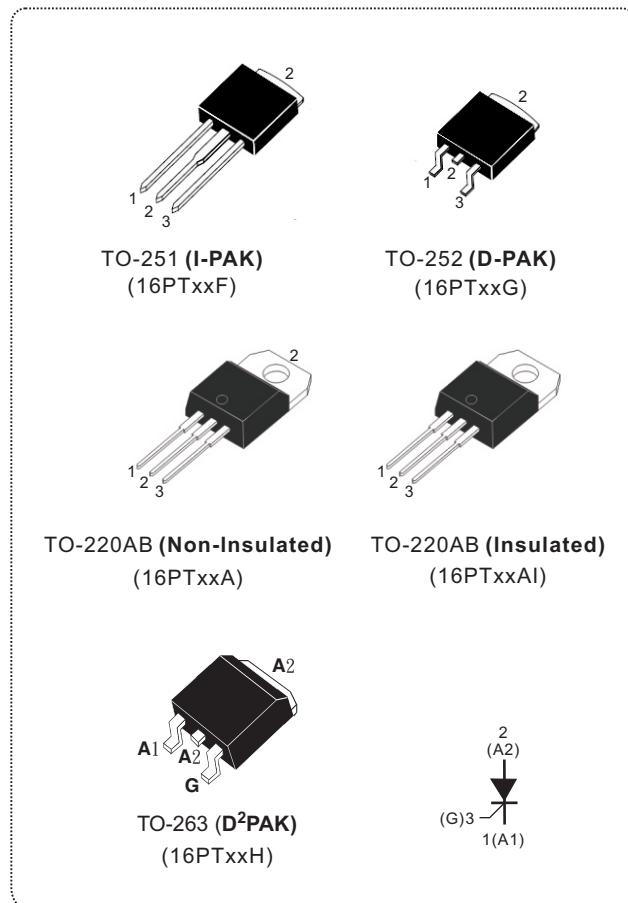
### Main Features

Symbol	Value	Unit
$I_{T(RMS)}$	16	A
$V_{DRM}/V_{RRM}$	600 to 1000	V
$I_{GT}$	25	mA

### DESCRIPTION

The 16PT series of silicon controlled rectifiers are high performance glass passivated technology, and are suitable for general purpose applications.

Using clip assembly technology, they provide a superior performance in surge current capabilities.



ABSOLUTE MAXIMUM RATINGS					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUE	UNIT
RMS on-state current full sine wave (180° conduction angle)	$I_{T(RMS)}$	TO-251/TO-252 TO-220AB/TO-263	$T_c=110^\circ C$	16	A
		TO-220AB insulated	$T_c=86^\circ C$		
Average on-state current (180° conduction angle)	$I_{T(AV)}$	TO-251/TO-252 TO-220AB/TO-263	$T_c=110^\circ C$	10	A
		TO-220AB insulated	$T_c=86^\circ C$		
Non repetitive surge peak on-state current (full cycle, $T_j$ initial = 25°C)	$I_{TSM}$	$F=50$ Hz	$t = 20$ ms	190	A
		$F=60$ Hz	$t = 16.7$ ms	200	
$I^2t$ Value for fusing	$I^2t$	$t_p = 10$ ms		180	$A^2s$
Critical rate of rise of on-state current $I_G = 2xI_{GT}$ , $t \leq 100$ ns	$dl/dt$	$F = 60$ Hz	$T_j = 125^\circ C$	50	$A/\mu s$
Peak gate current	$I_{GM}$	$T_p = 20$ $\mu s$	$T_j = 125^\circ C$	4	A
Maximum gate power	$P_{GM}$	$T_p = 20\mu s$	$T_j = 125^\circ C$	10	W
Average gate power dissipation	$P_{G(AV)}$	$T_j = 125^\circ C$		1	W
Repetitive peak off-state voltage	$V_{DRM}$	$T_j = 125^\circ C$		600 to 1000	V
Repetitive peak reverse voltage	$V_{RRM}$				
Storage temperature range	$T_{stg}$			- 40 to + 150	$^\circ C$
Operating junction temperature range	$T_j$			- 40 to + 125	

ELECTRICAL SPECIFICATIONS ( $T_J = 25^\circ C$ unless otherwise specified)					
SYMBOL	TEST CONDITIONS			16PTxxxx	Unit
$I_{GT}$	$V_D = 12V$ , $R_L = 33\Omega$		Min.	2	mA V
$V_{GT}$			Max.	15	
$V_{GD}$			Max.	1.3	
$I_H$	$I_T = 500mA$ , Gate open		Max.	40	mA
$I_L$	$I_G = 1.2 \times I_{GT}$		Min.	60	mA
$dV/dt$	$V_D = 67\% V_{DRM}$ , Gate open		$T_J = 125^\circ C$	Min.	500 V/ $\mu s$
$V_{TM}$	$I_T = 32A$ , $t_P = 380\mu s$		$T_J = 25^\circ C$	Max.	1.6 V
$I_{DRM}$	$V_D = V_{DRM}$ , $V_R = V_{RRM}$ $R_{GK} = 220\Omega$		$T_J = 25^\circ C$	Max.	5 $\mu A$
$I_{RRM}$			$T_J = 125^\circ C$	Max.	2 mA
$V_{to}$	Threshold Voltage		$T_J = 125^\circ C$	Max.	0.77 V
$R_d$	Dynamic Resistance		$T_J = 125^\circ C$	Max.	23 m $\Omega$

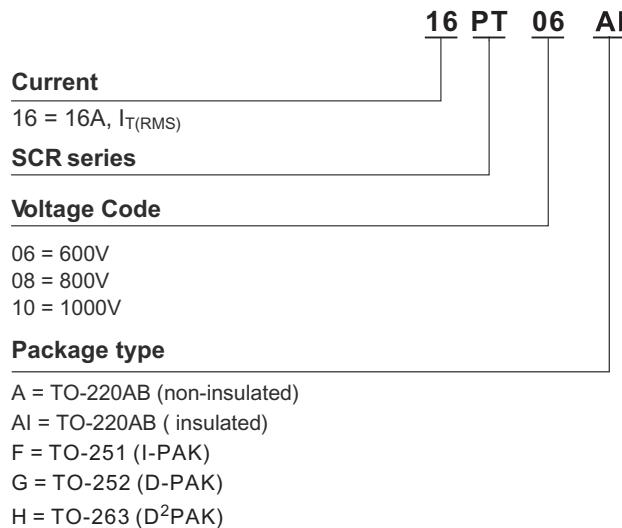
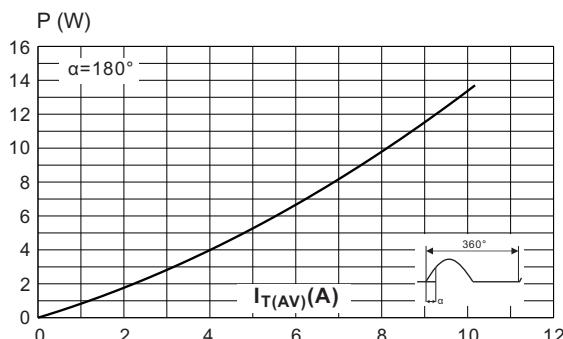
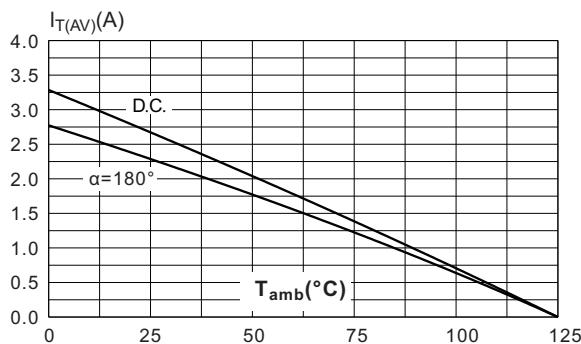
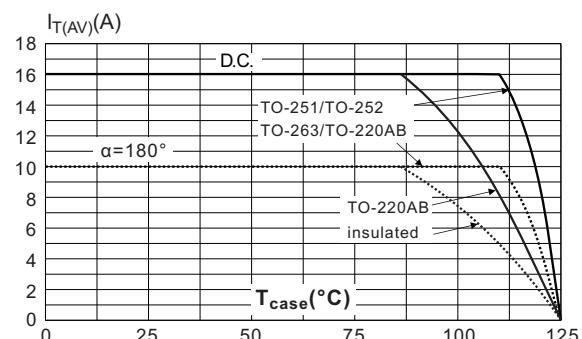
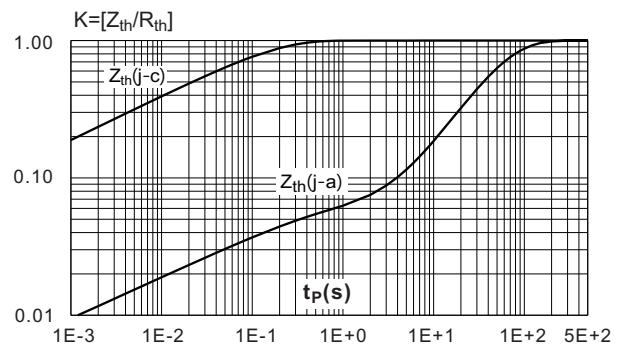
THERMAL RESISTANCE					
SYMBOL	Parameter			VALUE	UNIT
$R_{th(j-c)}$	Junction to case (DC)		IPAK/DPAK/TO-220AB/TO-263		1.1 $^\circ C/W$
$R_{th(j-a)}$	Junction to ambient		$S = 1 \text{ cm}^2$	TO-263(D <sup>2</sup> PAK)	45
			$S = 0.5 \text{ cm}^2$	TO-252(D-PAK)	70
			TO-220AB		60
			TO-251(I-PAK)		100

S=Copper surface under tab

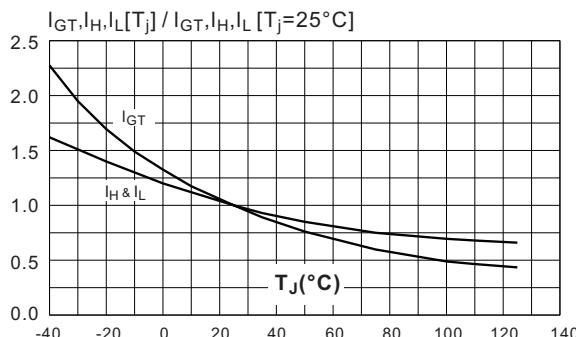
PRODUCT SELECTOR					
PART NUMBER	VOLTAGE (xx)			SENSITIVITY	PACKAGE
	600 V	800 V	1000 V		
16PTxxA/16PTxxAI	V	V	V	25 mA	TO-220AB
16PTxxF	V	V	V	25 mA	I-PAK
16PTxxG	V	V	V	25 mA	D-PAK
16PTxxH	V	V	V	25 mA	D <sup>2</sup> PAK

ORDERING INFORMATION					
ORDERING TYPE	MARKING	PACKAGE	WEIGHT	BASE Q'TY	DELIVERY MODE
16PTxxA	16PTxxA	TO-220AB	2.0g	50	Tube
16PTxxAI	16PTxxAI	TO-220AB (insulated)	2.3g	50	Tube
16PTxxF	16PTxxF	TO-251(I-PAK)	0.40g	80	Tube
16PTxxG	16PTxxG	TO-252(D-PAK)	0.38g	80	Tube
16PTxxH	16PTxxH	TO-263(D <sup>2</sup> PAK)	2.0g	50	Tube

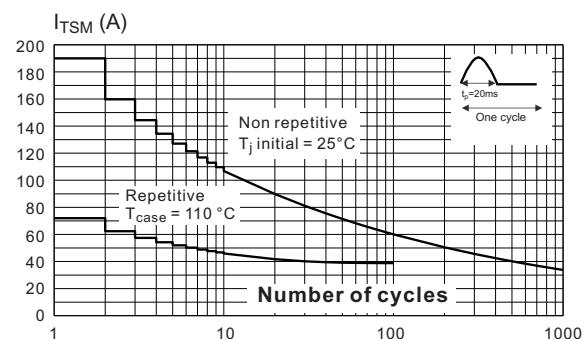
Note: xx = voltage

**ORDERING INFORMATION SCHEME**

**Fig.1 Maximum average power dissipation versus average on-state current.**

**Fig.3 Average and D.C. on-state current versus ambient temperature.  
(copper surface under tab:  $S=1\text{cm}^2$ )  
(D<sup>2</sup>PAK)**

**Fig.2 Average and D.C. on-state current versus case temperature.**

**Fig.4 Relative variation of thermal impedance versus pulse duration.**


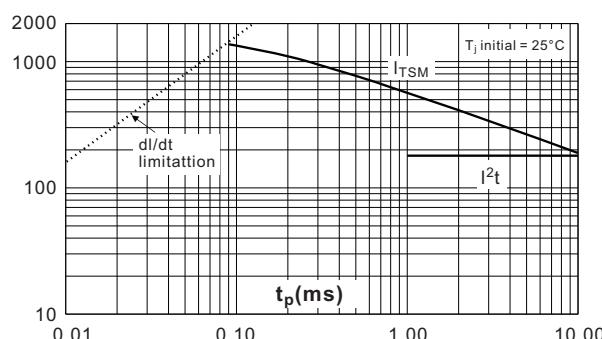
**Fig.5 Relative variation of gate trigger current, holding current and latching current and latching current versus junction temperature.**



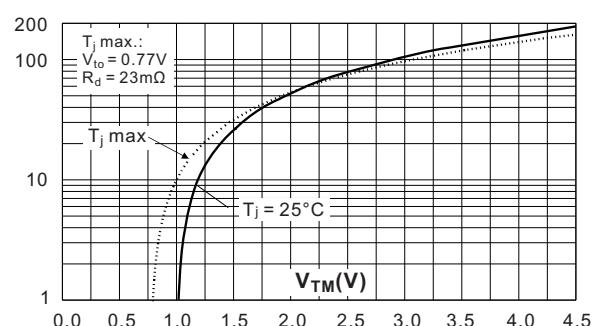
**Fig.6 Surge peak on-state current versus number of cycles.**



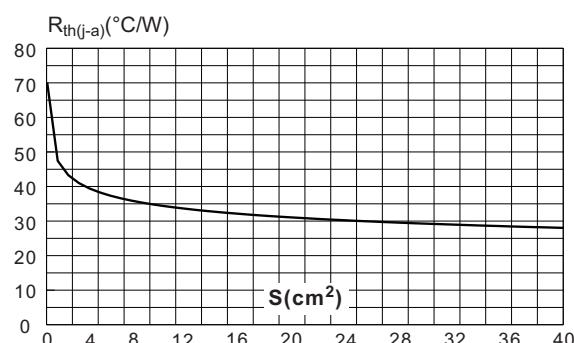
**Fig.7 Non-repetitive surge peak on-state current for a sinusoidal pulse with width  $t_p < 10$  ms, and corresponding values of  $I^2t$**



**Fig.8 On-state characteristics (maximum values)**

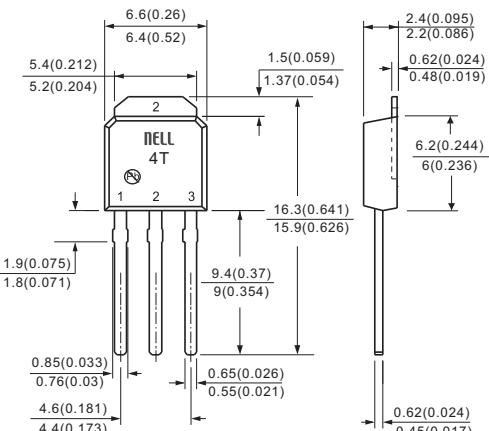


**Fig.9 Thermal resistance junction to ambient versus copper surface under tab (epoxy printed circuit board Fr4, copper thickness:35 µm)(D<sup>2</sup>PAK)**

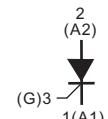
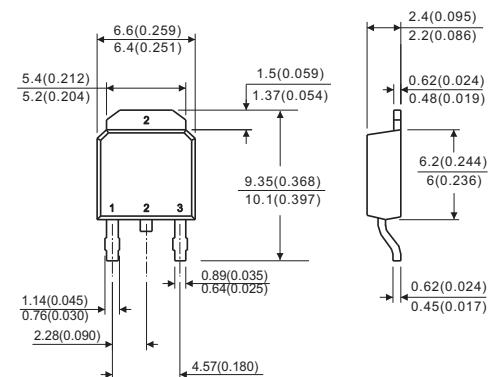


## Case Style

**TO-251  
(I-PAK)**

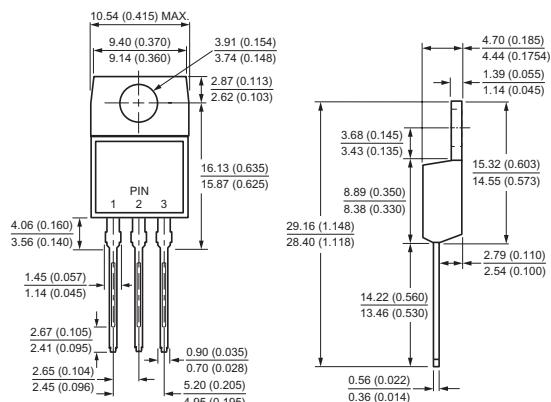
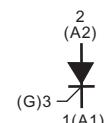
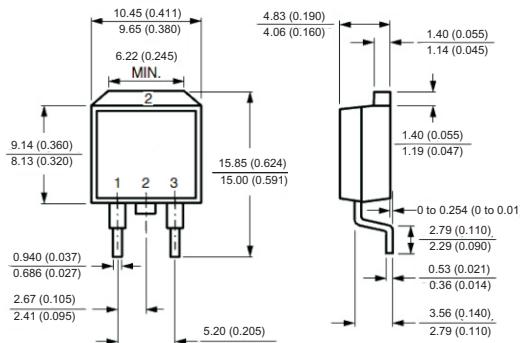


**TO-252  
(D-PAK)**



All dimensions in millimeters(inches)

## Case Style

**TO-220AB**

**TO-263(D<sup>2</sup>PAK)**


All dimensions in millimeters(inches)